



# SSL5231T

## Compact high power factor dimmable LED driver IC

Rev. 1 — 17 October 2014

Preliminary data sheet

## 1. General description

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The SSL5231T is a highly integrated, high-precision dimmable controller with an external MOSFET. It is intended to drive LED lamps in dimmable lighting applications up to 25 W. The SSL5231T is designed for high power factor, phase-dimmable applications.

The SSL5231T operates in Boundary Conduction Mode (BCM) with constant on-time control. It provides a constant output current control with good LED output current accuracy. Adaptive switching frequency gives freedom to choose the inductor, which enables the optimization of inductor size, efficiency and EMI.

The SSL5231T can start up and operate in switching mode directly from an external resistor without capacitor charge pump supply or auxiliary supply. This feature simplifies the  $V_{CC}$  supply. So, a low-cost off-the-shelf inductor can be used, which provides flexibility in application design.

## 2. Features and benefits

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- Supports most available dimming solutions
- Deep dimming level
- Flicker-free dimming
- Low component count ensuring a compact solution and small, single layer Printed-Circuit Board (PCB) footprint
- Excellent line regulation and load regulation and good LED output current accuracy
- Efficient BCM operation with:
  - ◆ No reverse recovery losses in freewheel diode
  - ◆ Zero Current Switching (ZCS) and Valley switching for turn-on of switch
  - ◆ Minimum inductance value and size required
  - ◆ High efficiency (up to 90 %)
  - ◆ Ultra low IC current during operation ( $< 165 \mu\text{A}$ )
- Many auto-recovery protections:
  - ◆ UnderVoltage LockOut (UVLO)
  - ◆ Cycle-by-cycle OverCurrent Protection (OCP)
  - ◆ Internal OverTemperature Protection (OTP)
  - ◆ Output OverVoltage Protection (OVP)
  - ◆ Output Short Protection (OSP)
- Compatible with wall switches with built-in standby indicator lights (Hotaru switch)
- IC lifetime meets and exceeds the required LED lamp lifetime



### 3. Applications

- The SSL5231T is intended for low-cost, non-isolated dimmable lighting applications that work from single mains voltage.

### 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage	operating range <a href="#">[1]</a>	9.9	-	16	V
$R_{DSon}$	on-state resistance	source-switch				
		$T_j = 25\text{ }^{\circ}\text{C}$	-	0.81	-	$\Omega$
		$T_j = 125\text{ }^{\circ}\text{C}$	-	1.2	-	$\Omega$
$I_{I(SW)}$	input current on pin SW	duty cycle < 5 %	-2	-	+2	A
$V_{I(SW)}$	input voltage on pin SW	current limited at 8.8 mA; internal switch-off	-0.4	-	+22	V

[1] An internal clamp sets the supply voltage. The current into the VCC pin must not exceed the maximum  $I_{VCC}$  value (see [Table 4](#)).

### 5. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
SSL5231T	SO8	plastic surface-mounted package; 8 leads	SOT96-1

6. Block diagram

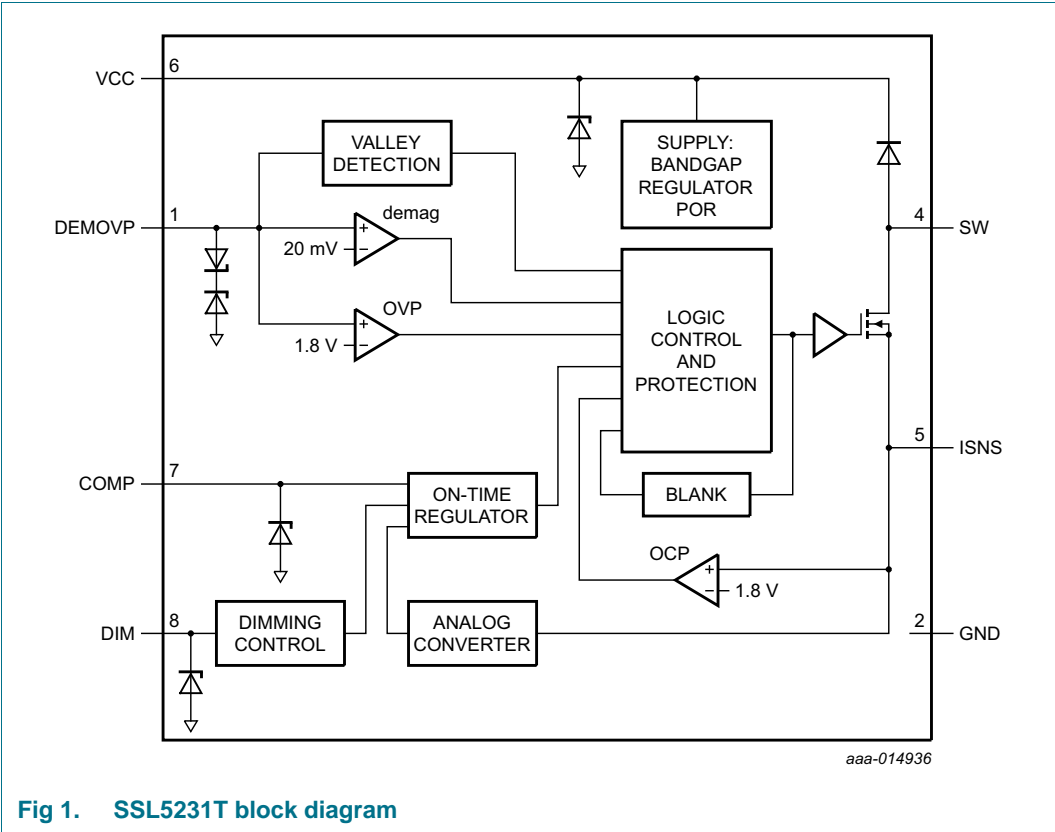


Fig 1. SSL5231T block diagram

7. Pinning information

7.1 Pinning

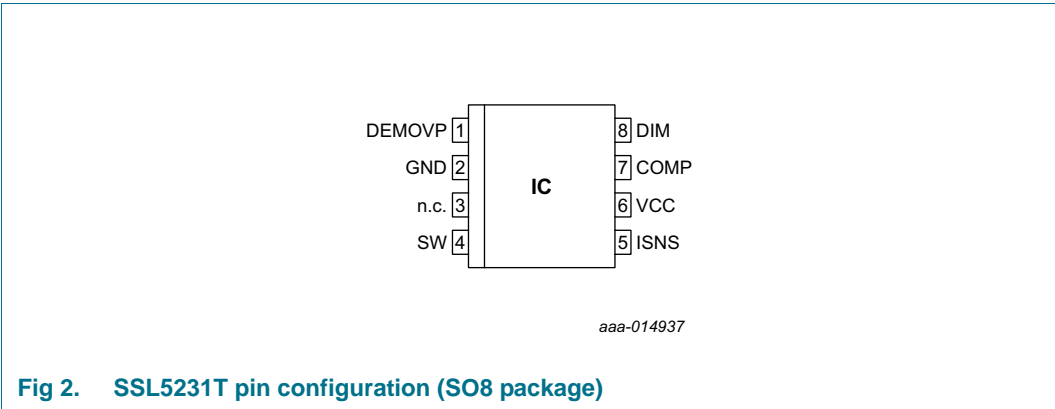


Fig 2. SSL5231T pin configuration (SO8 package)

## 7.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
DEMOVP	1	input from LED output for demagnetization timing, valley detection, and OVP
GND	2	ground
n.c.	3	not connected
SW	4	internal source-switch drain
ISNS	5	current sense input
VCC	6	supply voltage
COMP	7	loop compensation to provide stable response
DIM	8	dimming control input

## 8. Functional description

### 8.1 Converter operation

The converter in the SSL5231T is a source-switch, BCM, on-time controlled buck-boost system. [Figure 3](#) shows the basic application diagram. To save IC supply current, an integrated source-switch is used. It enables that even in switching mode only an external resistor is used as supply.

The converter operates at the boundary between Continuous Conduction Mode (CCM) and Discontinuous Conduction Mode (DCM). [Figure 5](#) shows the waveforms.

When the internal source-switch is switched on at  $t_0$ , the inductor current  $I_L$  proportionally to  $V_{in}$  builds up from zero during the source-switch on-time ( $t_0$  to  $t_1$ ). Energy is stored in the inductor. When the internal source-switch switches off at  $t_1$ ,  $I_L$  flows through the freewheeling diode and the output capacitor. It drops proportionally to the  $V_{out}$  value ( $t_2$  to  $t_3$ ). When  $I_L$  reaches zero at  $t_3$ , a new switching cycle is started after a short delay ( $t_3$  to  $t_0$ ) from valley detection.

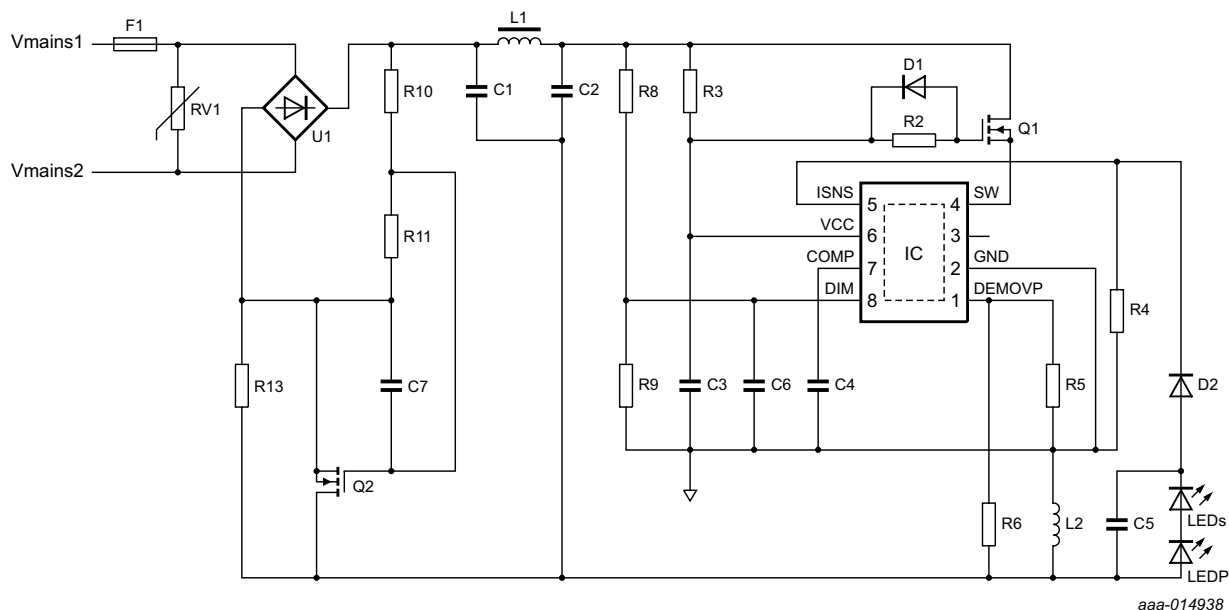


Fig 3. SSL5231T basic application diagram

## 8.2 On-time control

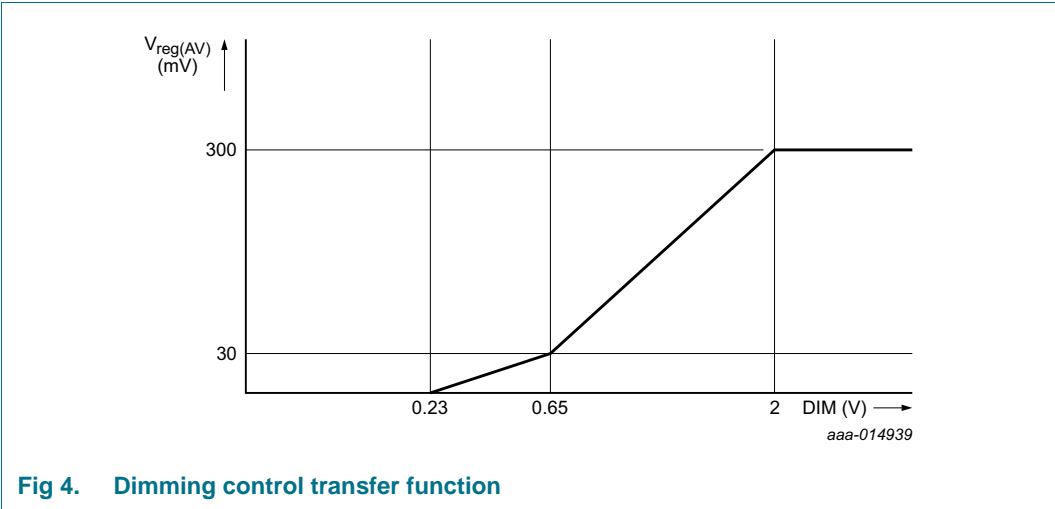
When measuring the inductor current  $I_L$  using sense resistor R4, the on-time is regulated so that the average ISNS voltage ( $V_{reg(AV)ISNS}$ ) is regulated to 300 mV during the off-time of the main switch. The average output current  $I_{out}$  can be calculated with [Equation 1](#):

$$I_{out} = \frac{0.3 \text{ V}}{R4} \quad (1)$$

## 8.3 Dimming control

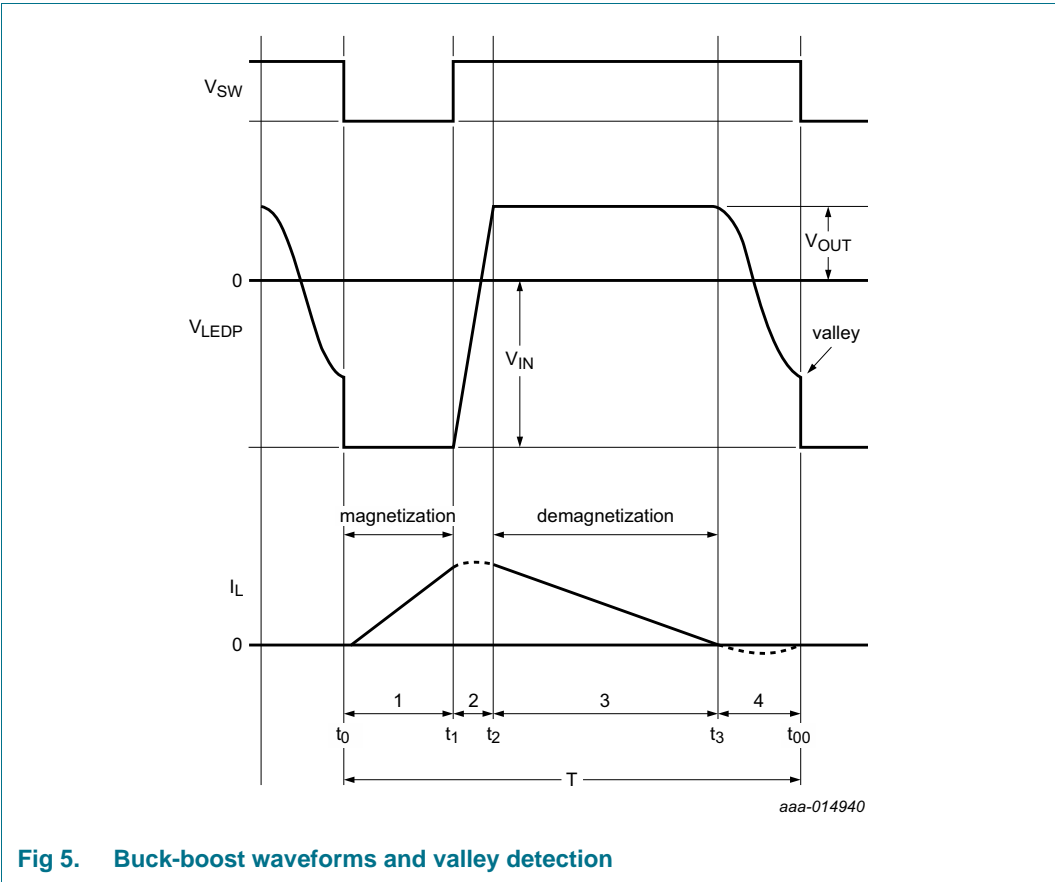
When measuring the phase-cut mains voltage using the DIM pin, the DIM voltage modulates the internal reference voltage. The dimmed output current  $I_{o(dimmed)}$  can be calculated with [Equation 2](#):

$$I_{o(dimmed)} = \frac{V_{reg(AV)}}{R4} \quad (2)$$



8.4 Valley detection

When  $I_L$  has decreased to zero at  $t_3$ , the LEDP voltage starts to oscillate around the 0 V level, with amplitude  $V_{OUT}$  and frequency ( $f_{ring}$ ). A special circuit called valley detection is integrated in the SSL5231T. It senses when the LEDP voltage reaches its lowest level (valley) at the DEMOVP pin. The internal source-switch is switched on again when the valley is detected. As a result, the switch-on switching losses are reduced.



## 8.5 Start-up current

The supply current for the IC is supplied by resistor  $R_{VCC}$ . Just before  $V_{CC}$  reaches the start-up voltage level ( $V_{startup}$ ), the IC draws an additional start-up current ( $I_{CC(startup)}$ ). So the supply current in operation is lower than the supply current during start-up conditions. It prevents lamp flicker when the mains voltage increases or decreases slowly.

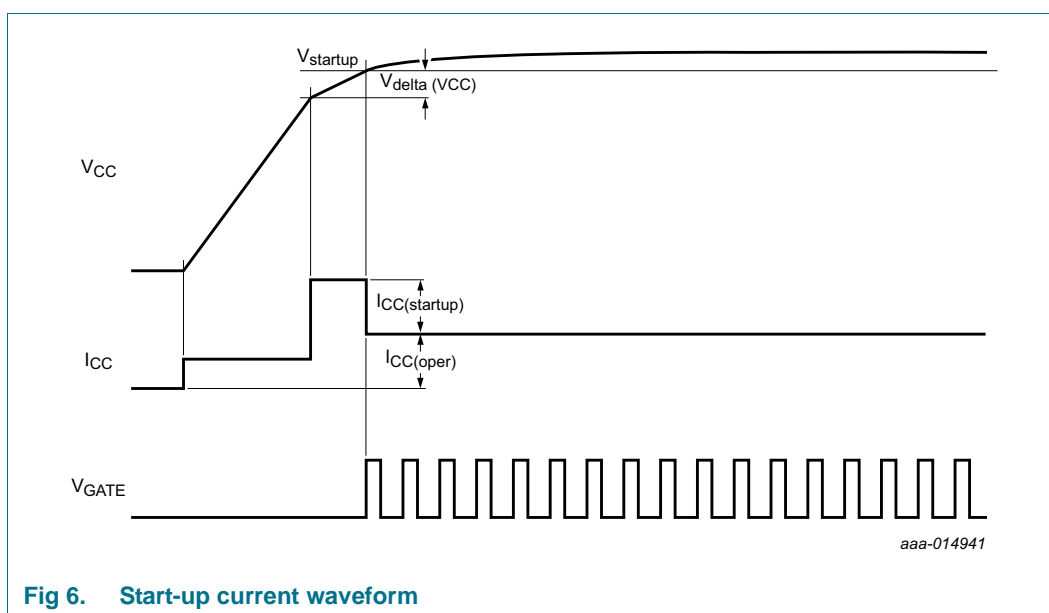


Fig 6. Start-up current waveform

## 8.6 Leading-Edge Blanking (LEB)

To prevent false detection of overcurrent, a blanking time following switch-on is implemented. When the internal source-switch turns on, a short current spike can occur because of the capacitive discharge of voltage over the drain and the source. It is disregarded during the LEB time ( $t_{leb}$ ).

## 8.7 Magnetization switching

When the mains voltage is very low, the system hardly delivers any energy to the LED. To improve the efficiency, maximum off-time ( $t_{off(max)}$ ) switching limits the switching frequency to  $< 25$  kHz.

## 8.8 Protections

The IC incorporates the following protections:

- UnderVoltage LockOut (UVLO)
- Cycle-by-cycle OverCurrent Protection (OCP)
- Internal OverTemperature Protection (OTP)
- Cycle-by-cycle maximum on-time protection
- Output OverVoltage Protection (OVP)
- Output Short Protection (OSP)

### 8.8.1 UnderVoltage LockOut (UVLO)

When the voltage on the VCC pin drops to below  $V_{th(UVLO)}$ , the IC stops switching. An attempt is made to restart IC when the  $V_{CC} > V_{startup}$ .

### 8.8.2 Cycle-by-cycle OverCurrent Protection (OCP)

The SSL5231T contains a built-in peak current detector. It triggers when the voltage at the ISNS pin reaches the peak level  $V_{ISNS(max)}$ . A resistor connected to the ISNS pin senses the current through the inductor  $I_L$ . The maximum current in inductor  $I_{L(max)}$  can be calculated with [Equation 3](#):

$$I_{L(max)} = \frac{V_{ISNS(max)}}{R4} \quad (3)$$

The sense circuit is activated after the LEB time ( $t_{leb}$ ). It automatically provides protection for maximum LED current during operation because the LED current is half the peak current by design. A propagation delay exists between overcurrent detection and the actual source-switch switch-off. Due to this delay, the actual peak current is slightly higher than the OCP level set by the resistor in series with the ISNS pin.

### 8.8.3 OverTemperature Protection (OTP)

When the internal OTP function is triggered at IC temperature  $T_{pl(IC)}$ , the converter stops switching. The IC resumes switching when the IC temperature drops to below  $T_{rst(IC)}$ .

### 8.8.4 Cycle-by-cycle maximum on-time protection

Measuring the inductor current  $I_L$  using sense resistor  $R_{sense}$  regulates the on-time. The on-time is limited to a fixed value ( $t_{on(max)}$ ). It protects the system and the IC when the ISNS pin is shorted or the system works at very low mains.

### 8.8.5 Output OverVoltage Protection (OVP)

Measuring the voltage at the DEMOVP pin during the secondary stroke gives an accurate output OVP. The resistive divider connected between the LEDP node and the DEMOVP pin sets the maximum LED voltage.

An internal counter prevents false OVP detection because of noise on the DEMOVP pin. After three continuous cycles with a DEMOVP pin voltage exceeding the OVP level, OVP is triggered.

OVP triggers a restart sequence: A discharge current ( $I_{CC(dch)}$ ) is enabled and discharges  $V_{CC}$  to below  $V_{rst(latch)}$ . When  $V_{rst(latch)}$  is reached, the system restarts.

### 8.8.6 Output Short Protection (OSP)

The converter operates in Discontinuous Conduction Mode (DCM). A new cycle is only started after the previous cycle has ended. Measuring the voltage on the DEMOVP pin detects the end of the cycle. When the DEMOVP pin voltage drops to below the demagnetization level ( $V_{th(comp)DEMOVP}$ ) and a valley is detected, a new cycle starts. The converter regulates the adjusted output current and the on-time is reduced to a safe value by this feedback. The reduced on-time in combination with a very long demagnetization period prevents the converter from any damage or excessive dissipation.



To prevent false demagnetization detection, a blanking time ( $t_{\text{sup(xfmr\_ring)}}$ ) is implemented at the start of the secondary stroke.

## 8.9 Supply management

The IC starts up when the voltage at the VCC pin exceeds  $V_{\text{startup}}$ . The IC locks out (stops switching) when the voltage at the VCC pin drops to below  $V_{\text{th(UVLO)}}$ . The hysteresis between the start and stop levels allows the VCC capacitor to supply the IC during zero-crossings of the mains.

The SSL5231T incorporates an internal VCC clamping circuit. The clamp limits the voltage on the VCC supply pin to the maximum value  $V_{\text{clamp(VCC)}}$ . If the maximum current of the external resistor minus the current consumption of the IC is lower than the limiting value of  $I_{\text{VCC}}$  in [Table 4](#), no external Zener diode is required.

## 9. Limiting values

**Table 4. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
<b>Voltages</b>					
$V_{\text{CC}}$	supply voltage	current limited <a href="#">[1][2]</a>	-0.4	+18	V
$V_{\text{I(SW)}}$	input voltage on pin SW	current limited <a href="#">[1][2]</a>	-0.4	+22	V
$V_{\text{I(ISNS)}}$	input voltage on pin ISNS		-0.4	+5	V
$V_{\text{IO(Comp)}}$	input/output voltage on pin COMP		-0.4	+5.3	V
$V_{\text{I(DEMOVP)}}$	input voltage on pin DEMOVP		-5	+5	V
$V_{\text{I(DIM)}}$	input voltage on pin DIM		-0.4	+5	V
<b>Currents</b>					
$I_{\text{I(VCC)}}$	input current on pin VCC		-	+8.8	mA
$I_{\text{I(SW)}}$	input current on pin SW	RMS current	-	380	mA
		duty cycle < 5 %	-2	+2	A
$I_{\text{I(ISNS)}}$	input current on pin ISNS	duty cycle < 5 %	-2	+2	A
<b>General</b>					
$P_{\text{tot}}$	total power dissipation	$T_{\text{amb}} < 75\text{ °C}$	-	0.28	W
$T_{\text{stg}}$	storage temperature		-55	+150	°C
$T_{\text{j}}$	junction temperature		-40	+160	°C

**Table 4. Limiting values ...continued**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
<b>ESD</b>					
V <sub>ESD</sub>	electrostatic discharge voltage	class 1			
		human body model [3]	-2000	+2000	V
		charged device model [4]	-500	+500	V

[1] The current into the VCC pin must not exceed the maximum I<sub>VCC</sub> value.

[2] An internal clamp sets the supply voltage and current limits.

[3] Equivalent to discharge a 100 pF capacitor through a 1.5 kΩ series resistor.

[4] Charged device model: equivalent to charging the IC up to 1 kV and the subsequent discharging of each pin down to 0 V over a 1 Ω resistor.

## 10. Thermal characteristics

**Table 5. Thermal characteristics**

Symbol	Parameter	Conditions	Typ	Unit
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air; JEDEC test board	159	K/W
R <sub>th(j-top)</sub>	thermal resistance from junction to top	top package temperature measured at the warmest point on top of the case	0.49	K/W

## 11. Characteristics

**Table 6. Characteristics**

T<sub>amb</sub> = 25 °C; V<sub>CC</sub> = 15 V; all voltages are measured with respect to ground pin (pin 5); currents are positive when flowing into the IC; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Supply (pin VCC)</b>						
V <sub>startup</sub>	start-up voltage		14.45	14.9	15.35	V
V <sub>th(UVLO)</sub>	undervoltage lockout threshold voltage		9.6	9.9	10.2	V
V <sub>I(VCC)</sub>	input voltage on pin VCC	delta voltage	0.17	0.30	0.43	V
V <sub>clamp(VCC)</sub>	clamp voltage on pin VCC	I <sub>I(VCC)</sub> = 2.6 mA	15.2	15.8	16.4	V
V <sub>rst(latch)</sub>	latched reset voltage		5.8	6.2	6.6	V
I <sub>CC(oper)</sub>	operating supply current	switching at 100 kHz	125	145	165	μA
I <sub>CC(startup)</sub>	start-up supply current		120	145	170	μA
I <sub>CC(dch)</sub>	discharge supply current	V <sub>CC</sub> = V <sub>rst(latch)</sub>	3.7	-	-	mA

**Table 6. Characteristics ...continued**

$T_{amb} = 25\text{ }^{\circ}\text{C}$ ;  $V_{CC} = 15\text{ V}$ ; all voltages are measured with respect to ground pin (pin 5); currents are positive when flowing into the IC; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Loop compensation (pin COMP)</b>						
$V_{ton(zero)}$	zero on-time voltage		1.9	2.0	2.1	V
$V_{ton(max)}$	maximum on-time voltage		3.8	4.0	4.2	V
$V_{clamp(COMP)}$	clamp voltage on pin COMP		4.3	4.7	5.1	V
$t_{on(max)}$	maximum on-time	$V_{IO(COMP)} = 4\text{ V}$	12.3	15.5	18.7	$\mu\text{s}$
$I_{O(COMP)}$	output current on pin COMP	$V_{I(ISNS)} = 0\text{ V}$ ; $V_{I(DIM)} > 2\text{ V}$	2.4	3.0	3.6	$\mu\text{A}$
$I_{dch(COMP)}$	Discharge current on pin COMP	$V_{I(DIM)} = 0\text{ V}$	350	550	750	nA
<b>Valley detection and overvoltage detection (pin DEMOVP)</b>						
$V_{th(ovp)}$	overvoltage protection threshold voltage		1.74	1.81	1.88	V
$N_{cy(ovp)}$	number of overvoltage protection cycles		-	3	-	-
$(dV/dt)_{vrec}$	valley recognition voltage change with time	[1]	-	-3.8	-	V/ $\mu\text{s}$
$V_{det(demag)}$	demagnetization detection voltage		4	18	32	mV
$t_{sup(xfmr\_ring)}$	transformer ringing suppression time		1.2	1.5	1.8	$\mu\text{s}$
<b>Current sensing (pin ISNS)</b>						
$V_{I(ISNS)min}$	minimum input voltage on pin ISNS		30	50	70	mV
$V_{I(ISNS)max}$	maximum input voltage on pin ISNS		1.7	1.8	1.9	V
$t_{on(min)}$	minimum on-time	[2]	310	410	510	ns
$t_d$	delay time	[2]	-	100	-	ns
$g_m(ISNS)$	ISNS transconductance	$V_{I(ISNS)}$ to $I_{O(COMP)}$	8.4	9.7	11	$\mu\text{A/V}$
$V_{reg(max)ISNS}$	maximum regulation voltage on pin ISNS	$V_{I(DIM)} > 2\text{ V}$	0.298	0.31	0.324	V
<b>Dimming control (pin DIM)</b>						
$G_{DIM}$	gain on pin DIM	gain 1; $V_{I(DIM)}$ to $V_{reg(AV)ISNS}$ ; $0.65\text{ V} < V_{DIM} < 2\text{ V}$	0.19	0.2	0.21	V/V
		gain 2; $V_{I(DIM)}$ to $V_{reg(AV)ISNS}$ ; $0.25\text{ V} < V_{DIM} < 0.6\text{ V}$	0.058	0.07	0.092	V/V
$V_{clamp(DIM)}$	clamp voltage on pin DIM	$I_{I(DIM)} = 200\text{ }\mu\text{A}$	3.8	4.0	4.2	V
<b>Driver (pin SW)</b>						
$R_{DSon}$	on-state resistance	$T_j = 25\text{ }^{\circ}\text{C}$	-	0.81	0.9	$\Omega$
		$T_j = 125\text{ }^{\circ}\text{C}$	-	1.2	-	$\Omega$
$t_{off(max)}$	maximum off-time		30	40	50	$\mu\text{s}$

**Table 6. Characteristics ...continued**

$T_{amb} = 25\text{ }^{\circ}\text{C}$ ;  $V_{CC} = 15\text{ V}$ ; all voltages are measured with respect to ground pin (pin 5); currents are positive when flowing into the IC; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Temperature protection</b>						
$T_{pl(IC)}$	IC protection level temperature		140	150	165	$^{\circ}\text{C}$
$T_{rst(IC)}$	IC reset temperature		106	118	130	$^{\circ}\text{C}$

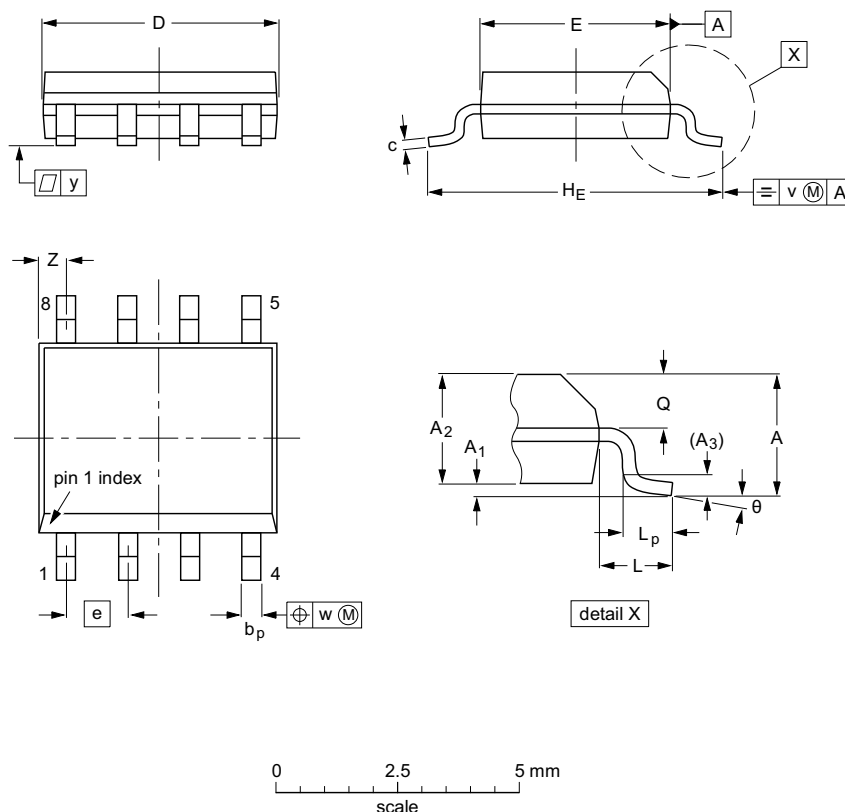
[1] Guaranteed by design.

[2]  $t_{leb} = t_{on(min)} - t_d$

## 12. Package outline

SO8: plastic small outline package; 8 leads; body width 3.9 mm

SOT96-1



**DIMENSIONS** (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	5.0 4.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.20 0.19	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

**Notes**

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT96-1	076E03	MS-012				99-12-27- 03-02-18

**Fig 7. Package outline SOT96-1 (SO8)**

## 13. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
SSL5231T v.1	20141017	Preliminary data sheet	-	-

## 14. Legal information

### 14.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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